

PRODUCT SPECIFICATION

16*2 Characters COB LCD MODULE MODEL: LT-1602E2-801 Ver:1.4

< \diamond > Finally Specification

	CUSTOMER'S	S APPROVAL
CUSTOMER :		
SIG	NATURE:	DATE:

APPROVED	PM	PD	PREPARED
BY	REVIEWD	REVIEWD	Ву

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• This specification is subject to change without notice. Please contact LT or its representative before designing your product based on this specification.

Revision Status

Version	Revise Date	Page	Content	Modified By
Ver 1.0	2017-09-15		First Issued	
Ver 1.1	2018-06-12	4-10,18	Modify IC , electrical parameters and sample NO.; update outline dimension	
	1			

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1. FEATURES

The features of LCD are showed as follows

- * Display mode
- : STN /Blue /Transmisstive /Negative * Controller IC : AIP31066(English-Japanese)
- * Display format
- : 16X2 Characters * Interface Input Data : 4 bit or 8 bit MPU
- * Driving Method
 - : 1/16Duty, 1/5Bias
- * Viewing Direction : 6 O'clock
- * Backlight
- * Sample NO.
- : 2 LED/Side White
- : C1602A4SGW6B-B5_02/20180606

2. MECHANICAL SPECIFICATIONS

ltem	Specification	Unit
Module Size	122(W) x 44(H) x 13MAX (D)	mm
Viewing Area	99(W) x 25(H)	mm
Activity Display Area	94.84 (W) x 20(H)	mm
Character Font	5 x 8 Dots	-
Character Size	4.84(W) x 9.66(H)	mm
Character Pitch	6(W) x 10.34(H)	mm
Dot Size	0.92(W) x 1.1(H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C)

ltem	Symbol	Sta			
item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	Vdd – Vss	-0.3	-	7.0	V
Supply Voltage For LCD Drive	V_{LCD}	Vdd -15	-	VDD +0.3	V
Input Voltage	Vin	-0.3	-	Vdd+0.3	V
Operating Temp.	Тор	-20	-	+70	°C
Storage Temp.	Tst	-30	-	+80	°C

*NOTE: The response time will be extremely slow when the operating temperature is around -10° C, and the back ground will become darker at high temperature operating.

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3-2 ELECTRICAL CHARACTERISTICS

ltem		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic supply	Voltage	Vdd – Vss		4.5	5	5.5	V
LCD Drive V	oltage	V _{LCD}		4.3	4.5	4.7	V
	"H" Level	V _{IH}	Ta = 25 °C	2.2	-	VDD	V
Input Voltage	"L" Level	V _{IL}	$VDD=5V\pm10\%$	-0.3	-	0.6	V
Frame Freq	uency	f _{FLM}		-	84.3	-	Hz
Current Const	umption	I _{DD}		-	1.33	-	mA

3-3 BACKLIGHT

3-3-1. Absolute Maximum Ratings

ltem	Symbol	Condition	min	Тур	Max	Unit
Forward Current	IF		-	-	40	mA
Forward Voltage	VF	Ta = 25 °C	-	-	3.5	V
Power Dissipation	PD	Ta = 25 C	-	-	146	mW
Reverse Voltage	VR		-	-	5	V

3-3-2. Electrical-optical Characteristics

Item	Symbol	Condition	min		Тур		Мах		Unit
Forward Voltage	VF		2.	2.9 3.2		3.2		3.5	
Average Luminous Intensity	Lv	lf=20*2 mA Ta = 25 °C	10	100		-		-	cd/m ²
Colour coordonate	-		Х	Y	Х	Y	Х	Y	-
			0.25	0.25	0.28	0.28	0.32	0.32	

*NOTE: The brightness is measured without LCD panel

For operation above 25 °C, The lfm & Pd must be derated , the current derating is -0.36mA/ °C for DC drive and -0.86mA/ °C for Pulse drive ,the Power dissipation is -0.75mW/ °C. The product working current must not more than the 60% of the lfm or lfp according to the working temperature.

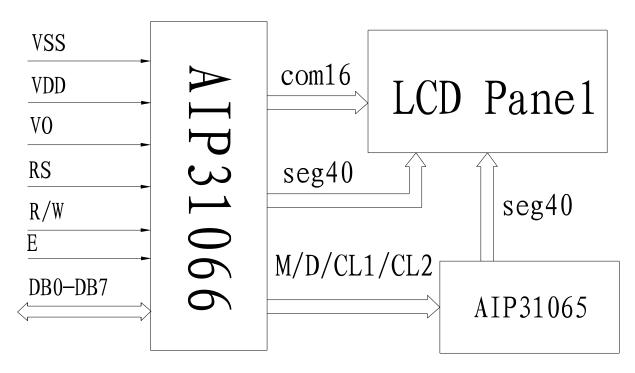
Backlight lifetime means luminance value larger than half of the original after 20000 hours' continuous working.

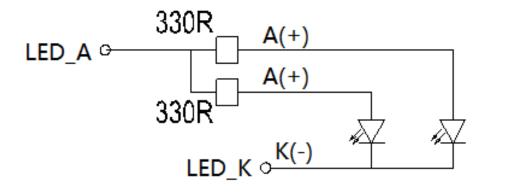
4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

4-1 INTERFACE PIN FUNCTION DESCRIPTION

PIN NO.	SYMBOL	FUNCTIONS
1	VSS	Ground
2	VDD	Supply voltage for logical circuit
3	V0	Supply voltage for LCD driving
4	RS	A signal for selecting registers. 1: Data Register (for read and write) 0: Instruction Register (for write)
5	R/W	A signal for selecting read or write actions.1: Read, 0: Write.
6	E	A enable signal for reading or writing data.
7~14	DB0~DB7	8 Bit Data Bus
15	LED_A	Backlight(+5.0V)
16	LED_K	Backlight(0V)

4-2 BLOCK DIAGRAM



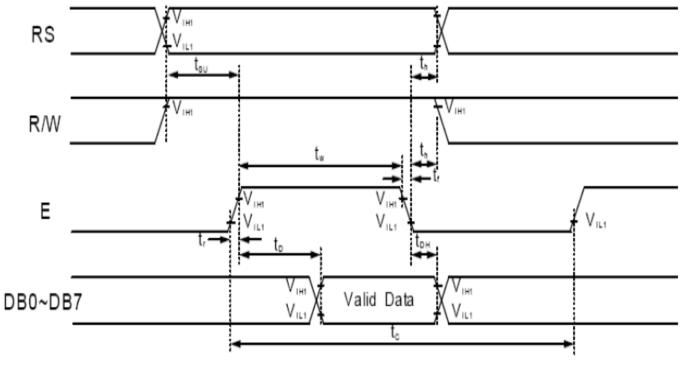


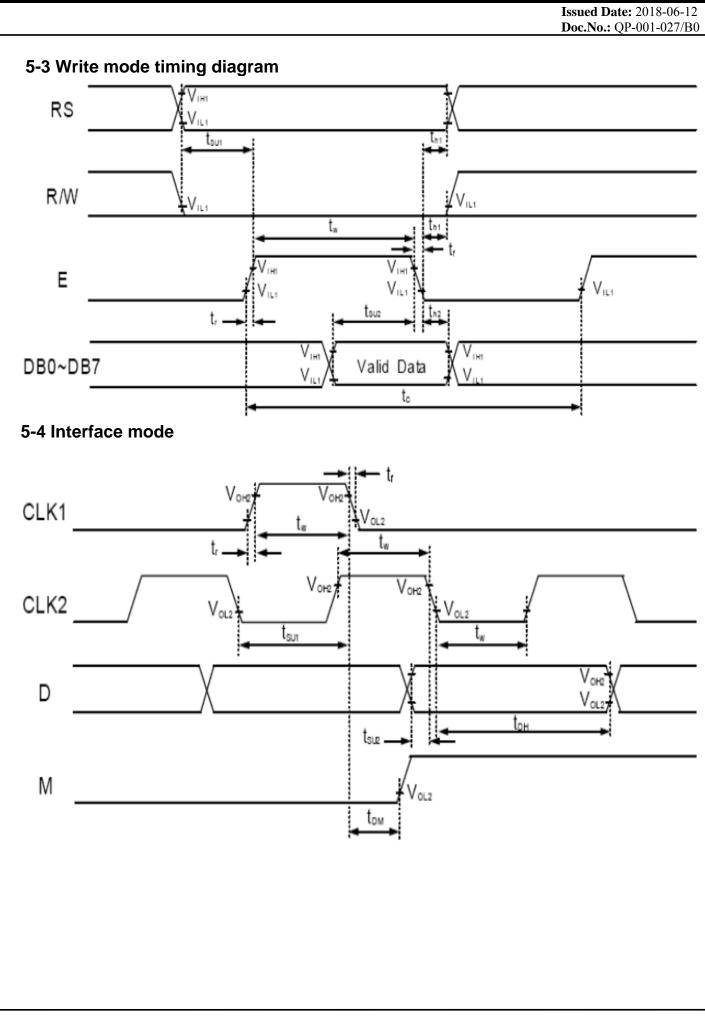
5. TIMING CHARACTERISTICS

5-1 Read/Write mode

Mode	Characteristic	Symbol	Min.	Тур.	Max.	Unit	
	E Cycle Time	tc	500	<u> </u>	Max. - 20 - - - 20 - 20 - 120 - 120 -		
	E Rise / Fall Time	Lycle Time tc 500 - - Rise / Fall Time t_{R}, t_{F} - - 20 Pulse Width (High, Low) t_w 230 - - V and RS Setup Time t_{su1} 40 - - V and RS Hold Time t_{H1} 10 - - V and RS Hold Time t_{H1} 10 - - vand RS Hold Time t_{H1} 10 - - vand RS Hold Time t_{H2} 10 - - vand RS Hold Time t_{H2} 10 - - vand RS Hold Time t_{H2} 10 - - value / Fall Time t_R, t_F - - 20 value / Vand RS Setup Time t_{gu} 40 - - V and RS Hold Time t_H 10 - - - vand RS Hold Time t_H 10 - - - vand RS Hold Time t_0 <td colspan="2"></td>					
	E Pulse Width (High, Low)						
Write Mode (Refer to Fig-1)	R/W and RS Setup Time	t _{su1}	40	- -	- 20 - - - - 20 - 20 - - - - 120	ns	
(10010110 Fig 1)	R/W and RS Hold Time	t _{en}	10	20			
	Data Setup Time	t _{su2}	80	5 - (5			
	Data Hold Time	t _{H2}	10	4			
	E Cycle Time	t,	500	<u>_</u>			
	E Rise / Fall Time	t _R , t _F	500 - - 500 - - 20 230 - - 20 230 - - 20 40 - - - 40 - - - 10 - - - 80 - - - 10 - - - 500 - - 20 230 - - 20 230 - - 20 10 - - 20 230 - - - 40 - - - 10 - - 120				
	$ \begin{array}{ c c c c c c c } \hline E \ Cycle \ Time & tc & 500 & - & - \\ \hline E \ Rise / \ Fall \ Time & t_{R_i} t_F & - & - & 20 \\ \hline E \ Pulse \ Width \ (High, \ Low) & t_w & 230 & - & - \\ \hline R/W \ and \ RS \ Setup \ Time & t_{su1} & 40 & - & - \\ \hline R/W \ and \ RS \ Hold \ Time & t_{H1} & 10 & - & - \\ \hline Data \ Setup \ Time & t_{su2} & 80 & - & - \\ \hline Data \ Hold \ Time & t_{H2} & 10 & - & - \\ \hline Data \ Hold \ Time & t_{H2} & 10 & - & - \\ \hline E \ Cycle \ Time & t_{R_i} \ t_F & - & - & 20 \\ \hline E \ Cycle \ Time & t_{R_i} \ t_F & - & - & 20 \\ \hline E \ Cycle \ Time & t_{R_i} \ t_F & - & - & 20 \\ \hline E \ Pulse \ Width \ (High, \ Low) & t_w \ 230 & - & - \\ \hline R/W \ and \ RS \ Setup \ Time & t_{R_i} \ t_F & - & - & 20 \\ \hline E \ Pulse \ Width \ (High, \ Low) & t_w \ 230 & - & - \\ \hline R/W \ and \ RS \ Setup \ Time & t_{Su} \ 40 & - & - \\ \hline R/W \ and \ RS \ Setup \ Time & t_H \ 10 & - & - \\ \hline Data \ Output \ Delay \ Time & t_0 \ - & - & 120 \\ \hline \end{array}$	Č					
Read Mode (Refer to Fig-2)	R/W and RS Setup Time	t _{su}	40	-23	- 20 - - - - 20 - - - - - 120	ns	
(Neier to Fig-2)	R/W and RS Hold Time	t _H	10		-		
	Data Output Delay Time	to	2		- 20 - - - - - 20 - - - - - - 120		
	Data Hold Time	t _{on}	5	-			

5-2 Read mode timing diagram





6 COMMAND LIST

Instruction				Inst	ructi	on C	ode				Description	Execution
Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	time (fosc= 270 kHz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM and set DDRAM address to '00H" from AC	1.53 ms
Return Home	0	0	0	0	0	0	0	0	1	-	Set DDRAM address to '00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.53 ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	SH	Assign cursor moving direction and enable the shift of entire display.	39 µs
Display ON/ OFF Control	0	0	0	0	0	0	1	D	с	в	Set display(D), cursor(C), and blinking of cursor(B) on/off control bit.	39 µs
Cursor or Display Shift	0	0	0	0	0	1	s/c	R/L	-	-	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	39 µs
Function Set	0	0	0	0	1	DL	N	F	-	-	Set interface data length (DL: 8-bit/4-bit), numbers of display line (N: 2-line/1-line) and, display font type (F:5×11dots/5×8 dots)	39 µs
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	39 µs
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	ACO	Set DDRAM address in address counter.	39 µs
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0 µs
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	43 µs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	DO	Read data from internal RAM (DDRAM/CGRAM).	43 µs

* "-" dont care

NOTE: When an MPU program with checking the Busy Flag(DB7) is made, it must be necessary 1/2Fosc is necessary for executing the next instruction by the falling edge of the 'E' signal after the Busy Flag (DB7) goes to "Low".

7. CHARACTER GENERATOR ROM

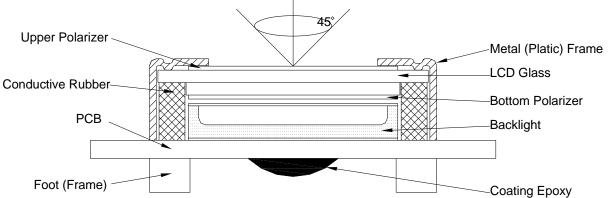
Upper 4 Lever Bits	00 00	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	11 00	1 101	1110	1111
xxxx00000	DG RAM (1)			0		P	٩	P				-	9	Ę	α	p
xxxx00001	(2)		•	1	A	Q	а	9				7	Ŧ	4	ä	q
xxxx0010	(3)						b				Г	1	'n	X	ß	8
xxxx0011	(4)		Ħ	3	C	S	C	S			L	7	Ŧ	ŧ	ε	60
xxxx0100	(5)		\$	4	D	Ţ	d	ť			λ.	Ι	ŀ	Þ	μ	Ω
xxxx0101	(6)		Ζ	5	Ε	U	e	u				7	;	l	G	ü
xxxx0110	(7)		8	6	F	Ų	f	Ų			7	ħ	₹	Ξ	ρ	Σ
xxxx0111	(8)		7	7	G	Ŵ	9	W			7	ŧ	7	7	9	π
xxxxx1000	(1)		C	8	H	Х	h	X			4	2	*	y	٦,	X
xxxx1001	(2))	9	Ι	Y	i	У			Ċ	ን	J	Iŀ	-1	Ч
xxxx1010	(3)		×		Ĵ	Ζ	j	Z			I		Ù	\boldsymbol{k}	j	Ŧ
xxxx1011	(4)		Ŧ	;	Κ	Ľ	k	{			*	ÿ	L		X	Я
xxxx1100	(5)		,	<		¥	1				Þ	Ð	7	7	¢	Ħ
xxxx1101	(6)		-	=	М]	M	}			ı	Z	٩	2	Ł	÷
xxxx1110	(7)			>	Ν	^	n	÷			3	t	ħ	•	ħ	
xxx1111	(8)		/	?	0	_	0	÷			'n	y	7	•	Ö	

Note: The user can specify any pattern for character-generator RAM.

8. QUALITY SPECIFICATIONS

8-1. LCM Appearance and Electric inspection Condition

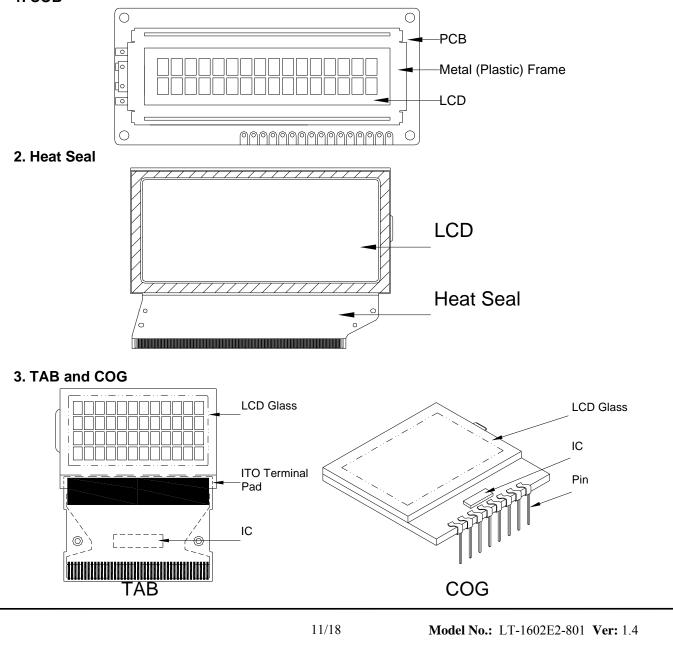
1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



2. View Angle: with in 45° around perpendicular line.

8-2. Definition





8-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (\parallel) ordinary single inspection is used.

2.Acceptance

Major defect:AQL = 0.65%Minor defect:AQL = 1.5%

8-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

2.SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	eight Exceed the dimension Of drawing	
Major	Component solder defect (missing , extra, wrong component or wrong orientation		Reject
Minor	Component position shift x component soldering pad x \rightarrow x \rightarrow x \rightarrow x \rightarrow y	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt component D soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component θ PAD ← PCB	<i>θ</i> ≤ 20°	Reject

letal (Pla	stic) Frame			Doc.No.: QP-
Defect	Inspection Item	l I	nspection Standa	rds
Major	Crack / breakage	Any	/where	Reject
		W	L	Acceptable of Scratch
		w<0.1mm	Any	Ignore
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1
		w <u>></u> 0.3mm	Any	0
			reater than 5mm. on the back sid ignored .	e of frame (n
			.9	Acceptable of Dents / Pricks
		⊕ <u><</u> 1.0mm		2
	Frame Dent , Prick	1.0<⊕ <u><</u> 1.5mm		1
Minor	$\Phi = \frac{L + W}{2}$	1.5	0	
	2	Note : 1. Above criteria applicable to any two de / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (visible) can be ignored		
Minor	Frame Deformation	Exceed the dimension of drawing		
Minor	Metal Frame Oxidation		Any rust	

4. Flexible Film Connector (FFC)

Defect	Insp	ection Item	Inspection Standa	rds
Minor	Tilte	Tilted soldering Within the angle +5°		Acceptable
Minor	Uneven s	older joint /bump		Reject
			Expose the conductive line	Reject
Minor	Hole	$\Phi = \frac{L + W}{2}$	Φ > 1.0mm	Reject
Minor	y_ <u>↓</u>	sition shift → ^Z ← ↓ □	Y > 1/3D	Reject
Minor		↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓	X > 1/2Z	Reject

5. Screw

Defect Inspection Item		Inspection Standards				
Major	Screw missing/loosen		Reject			
Minor	Screw oxidation	Any rust	Reject			
Minor	Screw deformation	Difficult to accept screw driver	Reject			

6. Heatseal TCP FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	Φ > 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift $Y \xrightarrow{-\psi} -\psi$	Y > 1/3D	Reject
Minor		X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards					
		Acceptable number of units					
		⊕ <u><</u> 0.10mm	Ignore				
		0.10<⊕ <u><</u> 0.15mm	2				
Minor	LED dirty, prick	0.15<⊕ <u><</u> 0.2mm	1				
		⊕>0.2mm	0				
		The distance between any two spots should be ≥ Any spot/dot/void outside of viewing area is acce					
Minor	Protective film tilt	Not fully cover LCD					
Major	COG coating	Not fully cover ITO circuit	Reject				

8. Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

Defect	Insp	ect Item			Ins	spectio	n St	tandards	5	
		* Glass Scratch	W		W <u><</u>	0.03	0.	03 <w<u><0.0</w<u>	5 V	N>0.05
		* Polarizer Scratch	L	L<5			L<3		Any	
Minor	Linear Defect	* Fiber and Linea	ACC. NO.			1		1		Reject
		material	Note	L is th	ne ler	ngth and V	V is th	ne width of	the de	efect
		* Foreign materia		⊕ <		0.1<⊕ <u><</u> (0.15	0.15<⊕ <u><</u> 0	.2	⊕>0.2
	Black Spot and	between glass and polarizer or glass		3E/ 100r	A / nm²	2		1		0
Minor	Polarizer Pricked	and glass * Polarizer hole o protuberance by external force	Note	Φ is the average diameter of the defect. Distance between two defects > 10mm.						
		* Unobvious	Ŧ		⊕ <u><</u> (0.3	0.3	<Φ <u><</u> 0.5	0.	.5< ⊕
	White Spot	transparant foreigr material betweer	1.00.	3E/	A / 10	00mm ²		1		0
Minor	and Bubble in polarizer	glass and glass o glass and polarizer * Air protuberance between polarize and glass	Note		Φ is the average diameter of the defect. Distance between two defects > 10mm.					
	Segment Defect		Φ	⊕ <u><</u> 0	.10	0.10<⊕ <u><</u> 0.2		20 0.20<⊕ <u><</u> 0.25		Φ >0 .
			ACC. NO.	3EA 100m	۹/ nm²	2		1		0
Minor				W is r	nore	than 1/2	segme	ent width		Reje
			Note	⊕= - Distar	~		vo de	fect is 10m	m	
			Φ	⊕ <u><</u> 0	Φ <u><</u> 0.10 0.10<Φ <u><</u>				<u><</u> 0.25	Ф >0 .:
	Protuberant	w w	W	Glu	Glue W <u><</u> 1/2 S W <u><</u> 0.2			W <u><</u> 1/2 W <u><</u> 0		Ignoi
Minor	Segment	$\Phi = (L + W) / 2$	ACC. NO.	3E/ 100n	A/ nm ²	2		1		0
			1. Seg	Segment						
			E			0.4mm		B <u><</u> 1.0mm		1.0mm
Minor	Assembly		B					-A<0.2		<0.25
	Mis-alignment	HB-1 -1 HA		Judge Acceptable Acceptable Acceptable Acceptable				spiable		
				rmatio						Reje
Minor	Stain on LCD Panel Surface		or a	similar	one	e. Otherw	vise, j	ed lightly w judged aco Vhite Spot"		

9. RELIABILITY

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	60℃, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	80°C, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20°C, 60min~70°C, 60min, 20 cycles.	2	GB/T2423.2 2 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	2	GB/T5170.1 4 -2009
8	Electrical Static Discharge	Air: \pm 8KV 150pF/330 Ω 5 times	2	GB/T17626.
0	Licentear Static Discharge	Contact: ± 4 KV 150pF/330 Ω 5 times	2	-2006
9	Drop Test(Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8 -1995

*NOTE:1) Above conditions are suitable for our company standard products.

2) For restrict products, the test conditions listed as above must be revised.

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10. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

- (2) Caution of LCD handling & cleaning
 - When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.
 - Isopropyl alcohol
 - Ethyl alcohol
 - Trichloro trifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water
- Ketone

- Aromatics

(3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

- (4) Packaging
 - Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
 - To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.
- (5) Caution for operation
 - It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
 - Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
 - If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
 - A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
 - Usage under the relative condition of 40°C, 50%RH or less is required.

(6) Storage

- In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.
 - Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
 - It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol. Which should be burned up later.
 - When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.
- (8) Other
 - After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

11. OUTLINE DIMENSION

NOTE: The dimension with"()" is reference

